

Super High Vertical Resolution Non-Contact 3D Surface Profiler BW-S500/BW-D500 Series

BW-S500 Super High Vertical Resolution Non-Contact 3D Surface Profiler BW-D500 Series

Nikon's proprietary scanning-type optical interference measurement technology achieves **1pm*** height resolution.

* Height resolution specified by algorithm

Quickly and accurately measures surface profile from sub-nano to millimeter height ranges, using a single measurement mode. Fully supports high-precision processing technology and advanced material development of the Materials Science field.



both smooth and rough surfaces.

Delivers super high-resolution height measurement with 4.19 Mpixel high-resolution camera



Six models available to match application and cost

Both the BW-S and BW-D are available in the six types shown below.

	Piezo	driven	Scanning						
	Objective	Noseniece	Z a	xis	XY axis				
	lens drive	drive	Manual	Electric	Manual	Electric			
3W-S501/D501	0		0		0				
3W- <mark>S502/D502</mark>	0			0	0				
3W-S503/D501	0			0		0			
3W-S505/D505		0	0		0				
3W-S506/D506		0		0	0				
3W-S507/D507		0		0		0			



High-precision/high-speed image acquisition via a two beam interference objective lens

The BW-S500 / D500 series uses a two beam interference objective lens and Nikon's proprietary algorithms to acquire height images with high speed and precision.



By overlaying the light returning from the reference mirror inside the objective lens and the light returning from the sample, the two beams overlap at the focal position and create interference.



pseudocolor

Laser mark Measurement range: 74×74µm (100×) Height range: 2µm





Enables wide-area analysis through the stitching of multiple height images.



Nosepiece drive piezo 505/506/507

BW-S500/BW-D500

Series

Allows easy switching of objective lens magnification.



An affordable objective lens drive piezo is also available





The brightness of the interference is highest at the focal position (0order interference position). The two beam interference objective lens is moved gradually by a piezo mechanism, and the position of greatest brightness is detected simultaneously and with ultra precision by all of the imaging elements







High Traceability and Repeatability

The BW-S500/BW-D500 series is calibrated by an 8nm or 8µm VLSI Step Height Standards sample, certified by the NIST. Achieves extremely high accuracy and repeatability as a height measurement system.





8nm Step Height Sample

VLSI (8nm Step Height Sample)



Measured value unsusceptible to variation of central wavelength of light source

With Nikon's proprietary technology, measurement values with the BW-S500/ BW-D500 series are independent of central wavelength of light source. Measurements can be done immediately after switching on illumination source.



Wide region configuration analysis with stitching

Electric XY stage and "Digital Stylus Imager 3" software allow stitching with BW-S503/507 and BW-D503/507.

Stitching can be done in both vertical and horizontal direction.



1pm height resolution achieved at magnifications from $2.5 \times$ to $100 \times$

Ultra high-precision allows for measurement of grade-0.1nm 3D roughness Sa from minimum magnification (4.4mm) to maximum magnification (111µm).



BW-S500/BW-D500

Series



Capable of ø20mm order wide region stitching at 10µm order range.

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Analytical software spanning basic measurement to advanced analysis

Image Transformer

Performs automatic measurement of distance, height and angle between two points specified by the cursor, as well as two-dimensional roughness (Ra, Rg, Rz) / three-dimensional roughness (Sa, Sg, Sz)



Display of cross-section profile and measurement results at position specified on the height image

3DViewer

The acquired height image is displayed in 3D.



Geometric Parameter Measurement

Through area and volume measurement of an irregular portion, as well as simultaneous analysis of the shapes of multiple irregular portions, uniformity and unevenness can be ascertained.



Display of the volume and area of specified indentations and protrusions

Surface Texture Analyzer

The low frequency / high frequency components of the height image are sampled, revealing approximate surface profile and allowing roughness analysis of detailed portions.



Zernike Polynomial Analyzer

From the height image of a spherical sample, the ideal spherical surface curve (geometric shape) for the sample's form is calculated, allowing analysis of the sample's surface roughness.



The height image and the calculated geometric shape are compared, and surface roughness is detected

Optical Ray Tracer

From a simulation of light rays when light is shone on the backside of a lens-shaped sample, light intensity distribution, luminous flux density, and other data can be analyzed for the specified cross section.



Layer Thickness Analyzer

Analysis of transparent films can be performed to ascertain the surface shape of each layer and investigate the film thickness distribution. Measurement of multiple layers is possible.



-1.5nm



		BW-S501	BW-S502	BW-S503	BW-S505	BW-S506	BW-S507	BW-D501	BW-D502	BW-D503	BW-D505	BW-D506	BW-D507	
Optical M	Aicroscope Unit	BW-LV150N	BW-FMA		BW-LV150N	BW-FMA		BW-LV150N	BW-FMA		BW-LV150N	BW-FMA		
	Piezo Driven	Objective lens driven			Nosepiece driven		Objective len	Objective lens driven		Nosepiece driven				
	Piezo Scanning Range	100µm						100µm						
	Z Axis	Manual Electric (standard stroke 20mm)		Manual	al Electric (standard stroke 20mm)		Manual	Electric (standard stroke 20mm)		Manual	Electric (standard stroke 20mm)			
	XY Axis	Manual	1	Electric (standard travel range 130×85mm)	Manual	1	Electric (standard travel range 130×85mm)	Manual	1	Electric (standard travel range 130×85mm)	Manual		Electric (standard travel range 130×85mm)	
Compute	er	High-performance specifications for BW												
Monitor		TFT 27" monitor												
Software	e	Bridgelements®												
Imaging	Camera	CMOS USB 3.0 camera						High-speed camera						
Number	of Pixels	2046×2046, 1022×1022 (selectable via software) 510 × 510												
Objective	Objective Lens Two beam interference objective lens (2.5×, 5×, 10×, 20×, 50×, 100×)													
Observat	tion and Measurement Range	e (Two Beam Int	terference Obj	ective Lens 1 F	ield of View)									
		2.5×	5×	10×	20×	50×	100×	2.5×	5×	10×	20×	50×	100×	
	Horizontal (H) µm	4448	2224	1112	556	222	111	2015	1007	503	251	100	50	
	Vertical (V) µm	4448	2224	1112	556	222	111	2015	1007	503	251	100	50	
	Working Distance (mm)	10.3	9.3	7.4	4.7	3.4	2.0	10.3	9.3	7.4	4.7	3.4	2.0	
	Numerical Aperture (NA)	0.075	0.13	0.3	0.4	0.55	0.7	0.075	0.13	0.3	0.4	0.55	0.7	
	Focal Depth (µm)	48.5	16.2	3.03	1.71	0.90	0.56	48.5	16.2	3.03	1.71	0.90	0.56	
	Pixel Resolution 2046× (µm) 1022×	2.18	1.09	0.55	0.28	0.11	0.06	3.96	1.98	0.99	0.50	0.20	0.10	
	1022	4.36	2.18	1.09	0.55	0.22	0.11							
	Optical Resolution (µm)	4.56	2.63	1.14	0.86	0.63	0.49	4.56	2.63	1.14	0.86	0.63	0.49	
Measure	ement Optical System	White light interferometry												
Algorithr Height R	mically-specified esolution	1pm (0.001nm)												
Effective (Environm	e Height Resolution nental Noise)	15pm (0.015nm) *When anti-vibration table is in environment not exceeding Vibration Criterion VC-C												
Step Mea	asurement Reproducibility	<i>σ</i> :8nm (8μ	m step measu	rement) *Whe	n anti-vibration	table is in enviro	onment not exceeding	g Vibration Criterion	VC-C					
Height M (1 Field of	leasurement Time f View, 10µm Scanning) 1022× 1022	38 seconds 4 seconds												
Height M	leasurement Range	90µm	Lower of obj lens working distance or 2	ective 20mm	90µm	Lower of obj lens working distance or 2	ective J 20mm	90µm	Lower of obj lens working distance or 2	ective J 20mm	90µm	Lower of obj lens working distance or 2	ective J 20mm	
Correctio	on	Plane Term Correction, Quartic Term Correction												
Digital E	nlargement	1/100 sub-pi	xel processing											
Roughne	ess Measurement	2-dimensiona	al roughness (Ra, Rq, Rz), 3	-dimensional r	oughness (Sa	, Sq, Sz)							
Profile D	isplay	Cursor measi	urement of hei	ght, distance,	and angle bet	ween two poir	nts; measurement	of approximate cir	cle radius of lo	ocation specifi	ed in the profi	e		
Output		Output of pro	cessed image	s and roughne	ess indices to a	an Excel file							-	
Automat	ic Processing	Automatic processing of multiple height images												
Three Di	mensional Display	With MS Dire	ct X											
Other An	alysis Software (Optional)	Geometric Parameter Measurement, Zernike Polynomial Analyzer, Optical Ray Tracer, Surface Texture Analyzer, Layer Thickness Analyzer, Reference Surface Correction, Hole Shape Analyzer												
Height C	alibration	Standard step sample (optional) made by VLSI Standards Inc.												
Anti-vibr	ration Mechanism (Optional)	Active vibration isolation table or passive vibration isolation table												
Power Se	ource	100-240±10%VAC												
Installati	ion Space	Approx. 1800(W) ×700(D) ×1600(H) mm												
Dimensio	ons/Weight	Microscope Unit: Approx. 500(W) ×560(D) ×700(H) mm / Approx. 23 kg												
		Computer Approx 172(0) x471(0) x404(1) m / Approx 20ka												

Series

BW-S500/BW-D500

BW-S500/BW-D500 Series

Dimensions



Specifications and equipment are subject to change without any notice or obligation on the part of the manufacturer. March 2014 ©2014 NIKON CORPORATION

N.B. Export of the products* in this catalog is controlled under the Japanese Foreign Exchange and Foreign Trade Law. Appropriate export procedures shall be required in case of export from Japan. *Products: Hardware and its technical information (including software)

🔥 WARNING

TO ENSURE CORRECT USAGE, READ THE CORRESPONDING MANUALS CAREFULLY BEFORE USING THE EQUIPMENT.



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